

Logic level TOPFET
SMD version of BUK119-50DL

BUK130-50DL

DESCRIPTION

Monolithic temperature and overload protected logic level power MOSFET in **TOPFET2** technology assembled in a 3 pin surface mount plastic package.

APPLICATIONS

General purpose switch for driving

- lamps
- motors
- solenoids
- heaters

in automotive systems and other applications.

FEATURES

- TrenchMOS output stage
- Current limiting
- Overload protection
- Overtemperature protection
- Protection latched reset by input
- 5 V logic compatible input level
- Control of output stage and supply of overload protection circuits derived from input
- Low operating input current permits direct drive by micro-controller
- ESD protection on all pins
- Overvoltage clamping for turn off of inductive loads

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V_{DS}	Continuous drain source voltage	50	V
I_D	Continuous drain current	20	A
P_D	Total power dissipation	90	W
T_j	Continuous junction temperature	150	°C
$R_{DS(ON)}$	Drain-source on-state resistance	28	mΩ
I_{ISL}	Input supply current $V_{IS} = 5\text{ V}$	650	μA

FUNCTIONAL BLOCK DIAGRAM

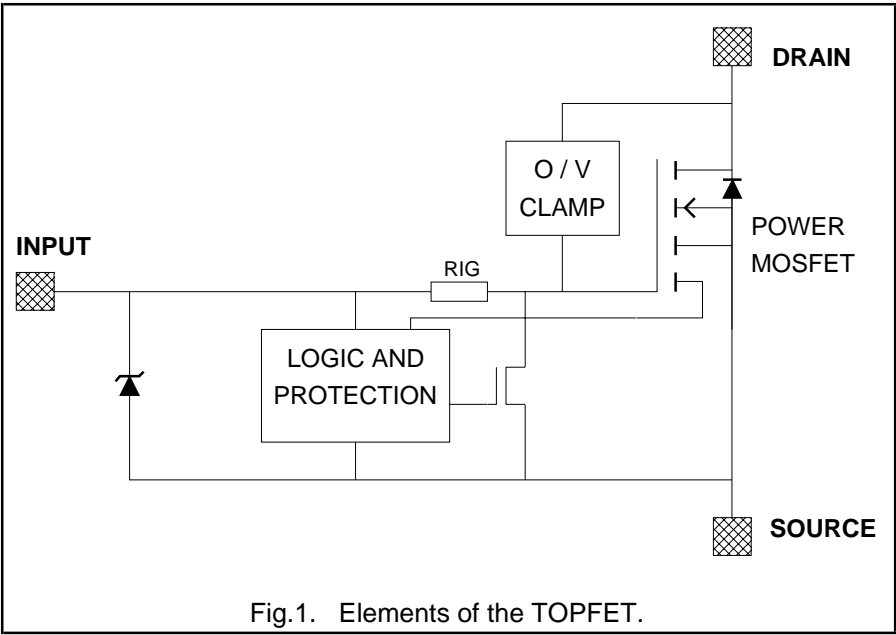
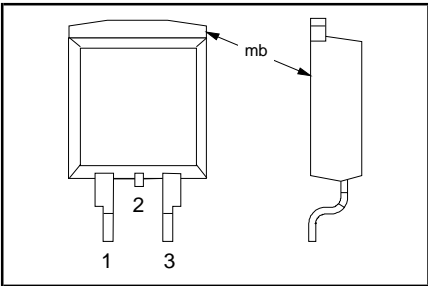


Fig.1. Elements of the TOPFET.

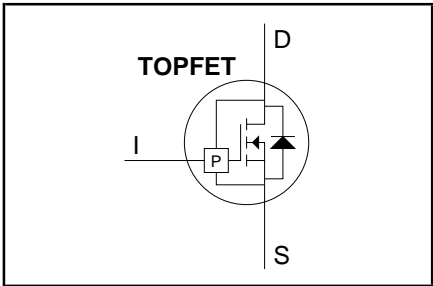
PINNING - SOT404

PIN	DESCRIPTION
1	input
2	drain
3	source
mb	drain

PIN CONFIGURATION



SYMBOL



Logic level TOPFET SMD version of BUK119-50DL

BUK130-50DL

LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS}	Continuous drain source voltage ¹		-	50	V
I_D	Continuous drain current	$V_{IS} = 5\text{ V}; T_{mb} = 25^\circ\text{C}$	-	self - limited	A
I_D	Continuous drain current	$V_{IS} = 5\text{ V}; T_{mb} \leq 121^\circ\text{C}$	-	20	A
I_I	Continuous input current		-5	5	mA
I_{IRM}	Repetitive peak input current	$\delta \leq 0.1, t_p = 300\text{ }\mu\text{s}$	-50	50	mA
P_D	Total power dissipation	$T_{mb} \leq 25^\circ\text{C}$	-	90	W
T_{stg}	Storage temperature		-55	175	$^\circ\text{C}$
T_j	Continuous junction temperature ²	normal operation	-	150	$^\circ\text{C}$
T_{sld}	Case temperature	during soldering	-	260	$^\circ\text{C}$

ESD LIMITING VALUE

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_C	Electrostatic discharge capacitor voltage	Human body model; $C = 250\text{ pF}; R = 1.5\text{ k}\Omega$	-	2	kV

OVERVOLTAGE CLAMPING LIMITING VALUES

At a drain source voltage above 50 V the power MOSFET is actively turned on to clamp overvoltage transients.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
E_{DSM}	Inductive load turn-off Non-repetitive clamping energy	$I_{DM} = 20\text{ A}; V_{DD} \leq 20\text{ V}$ $T_{mb} \leq 25^\circ\text{C}$	-	350	mJ
E_{DRM}	Repetitive clamping energy	$T_{mb} \leq 95^\circ\text{C}; f = 250\text{ Hz}$	-	45	mJ

OVERLOAD PROTECTION LIMITING VALUE

With an adequate protection supply provided via the input pin, TOPFET can protect itself from two types of overload - overtemperature and short circuit load.

SYMBOL	PARAMETER	REQUIRED CONDITION	MIN.	MAX.	UNIT
V_{DS}	Drain source voltage ³	$4\text{ V} \leq V_{IS} \leq 5.5\text{ V}$	0	35	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance Junction to mounting base	-	-	1.25	1.39	K/W
$R_{th\ j-a}$	Junction to ambient	minimum footprint FR4 PCB	-	50	-	K/W

¹ Prior to the onset of overvoltage clamping. For voltages above this value, safe operation is limited by the overvoltage clamping energy.

² A higher T_j is allowed as an overload condition but at the threshold $T_{j(TO)}$ the over temperature trip operates to protect the switch.

³ All control logic and protection functions are disabled during conduction of the source drain diode.

Logic level TOPFET SMD version of BUK119-50DL

BUK130-50DL

OUTPUT CHARACTERISTICS

Limits are for $-40^{\circ}\text{C} \leq T_{\text{mb}} \leq 150^{\circ}\text{C}$; typicals are for $T_{\text{mb}} = 25^{\circ}\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(\text{CL})\text{DSS}}$	Off-state Drain-source clamping voltage	$V_{\text{IS}} = 0 \text{ V}$				
		$I_{\text{D}} = 10 \text{ mA}$	50	-	-	V
I_{DSS}	Drain source leakage current	$I_{\text{DM}} = 4 \text{ A}; t_{\text{p}} \leq 300 \mu\text{s}; \delta \leq 0.01$	50	60	70	V
		$V_{\text{DS}} = 40 \text{ V}$ $T_{\text{mb}} = 25^{\circ}\text{C}$	-	-	100	μA
$R_{\text{DS(ON)}}$	On-state Drain-source resistance	$V_{\text{IS}} \geq 4.4 \text{ V}; t_{\text{p}} \leq 300 \mu\text{s}; \delta \leq 0.01$	-	-	52	$\text{m}\Omega$
		$I_{\text{DM}} = 10 \text{ A}$ $T_{\text{mb}} = 25^{\circ}\text{C}$	-	22	28	$\text{m}\Omega$

OVERLOAD CHARACTERISTICS

$V_{\text{IS}} = 5 \text{ V}; T_{\text{mb}} = 25^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{D}	Short circuit load Drain current limiting	$V_{\text{DS}} = 13 \text{ V}$	28.5	43	57	A
		$4.4 \text{ V} \leq V_{\text{IS}} \leq 5.5 \text{ V};$ $-40^{\circ}\text{C} \leq T_{\text{mb}} \leq 150^{\circ}\text{C}$	21	-	65	A
$P_{\text{D(TO)}}$ T_{DSC}	Overload protection Overload power threshold Characteristic time	device trips if $P_{\text{D}} > P_{\text{D(TO)}}$ which determines trip time ¹	75	185	250	W
			200	380	600	μs
$T_{\text{j(TO)}}$	Overttemperature protection Threshold junction temperature ²		150	170	-	$^{\circ}\text{C}$

¹ Trip time t_{dsc} varies with overload dissipation P_{D} according to the formula $t_{\text{dsc}} \approx T_{\text{DSC}} / \ln[P_{\text{D}} / P_{\text{D(TO)}}]$.

² This is independent of the dV/dt of input voltage V_{IS} .

Logic level TOPFET SMD version of BUK119-50DL

BUK130-50DL

INPUT CHARACTERISTICS

The supply for the logic and overload protection is taken from the input.

Limits are for $-40^{\circ}\text{C} \leq T_{\text{mb}} \leq 150^{\circ}\text{C}$; typicals are for $T_{\text{mb}} = 25^{\circ}\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{\text{IS(TO)}}$	Input threshold voltage	$V_{\text{DS}} = 5\text{ V}$; $I_{\text{D}} = 1\text{ mA}$ $T_{\text{mb}} = 25^{\circ}\text{C}$	0.6 1.1	- 1.6	2.4 2.1	V V
I_{IS}	Input supply current	normal operation; $V_{\text{IS}} = 5\text{ V}$ $V_{\text{IS}} = 4\text{ V}$	100 80	220 195	400 330	μA μA
I_{ISL}	Input supply current	protection latched; $V_{\text{IS}} = 5\text{ V}$ $V_{\text{IS}} = 3\text{ V}$	200 130	400 250	650 430	μA μA
V_{ISR}	Protection reset voltage ¹	reset time $t_{\text{r}} \geq 100\text{ }\mu\text{s}$	1.5	2	2.9	V
t_{lr}	Latch reset time	$V_{\text{IS1}} = 5\text{ V}$, $V_{\text{IS2}} < 1\text{ V}$	10	40	100	μs
$V_{\text{(CL)IS}}$	Input clamping voltage	$I_{\text{I}} = 1.5\text{ mA}$	5.5	-	8.5	V
R_{IG}	Input series resistance ² to gate of power MOSFET	$T_{\text{mb}} = 25^{\circ}\text{C}$	-	33	-	$\text{k}\Omega$

SWITCHING CHARACTERISTICS

$T_{\text{mb}} = 25^{\circ}\text{C}$; $V_{\text{DD}} = 13\text{ V}$; resistive load $R_{\text{L}} = 4\text{ }\Omega$. Refer to waveform figure and test circuit.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t_{don}	Turn-on delay time	$V_{\text{IS}} = 5\text{ V}$	-	25	50	μs
t_{r}	Rise time		-	50	100	μs
t_{doff}	Turn-off delay time	$V_{\text{IS}} = 0\text{ V}$	-	60	120	μs
t_{f}	Fall time		-	50	100	μs

¹ The input voltage below which the overload protection circuits will be reset.

² Not directly measureable from device terminals.

Logic level TOPFET
SMD version of BUK119-50DL

BUK130-50DL

MECHANICAL DATA

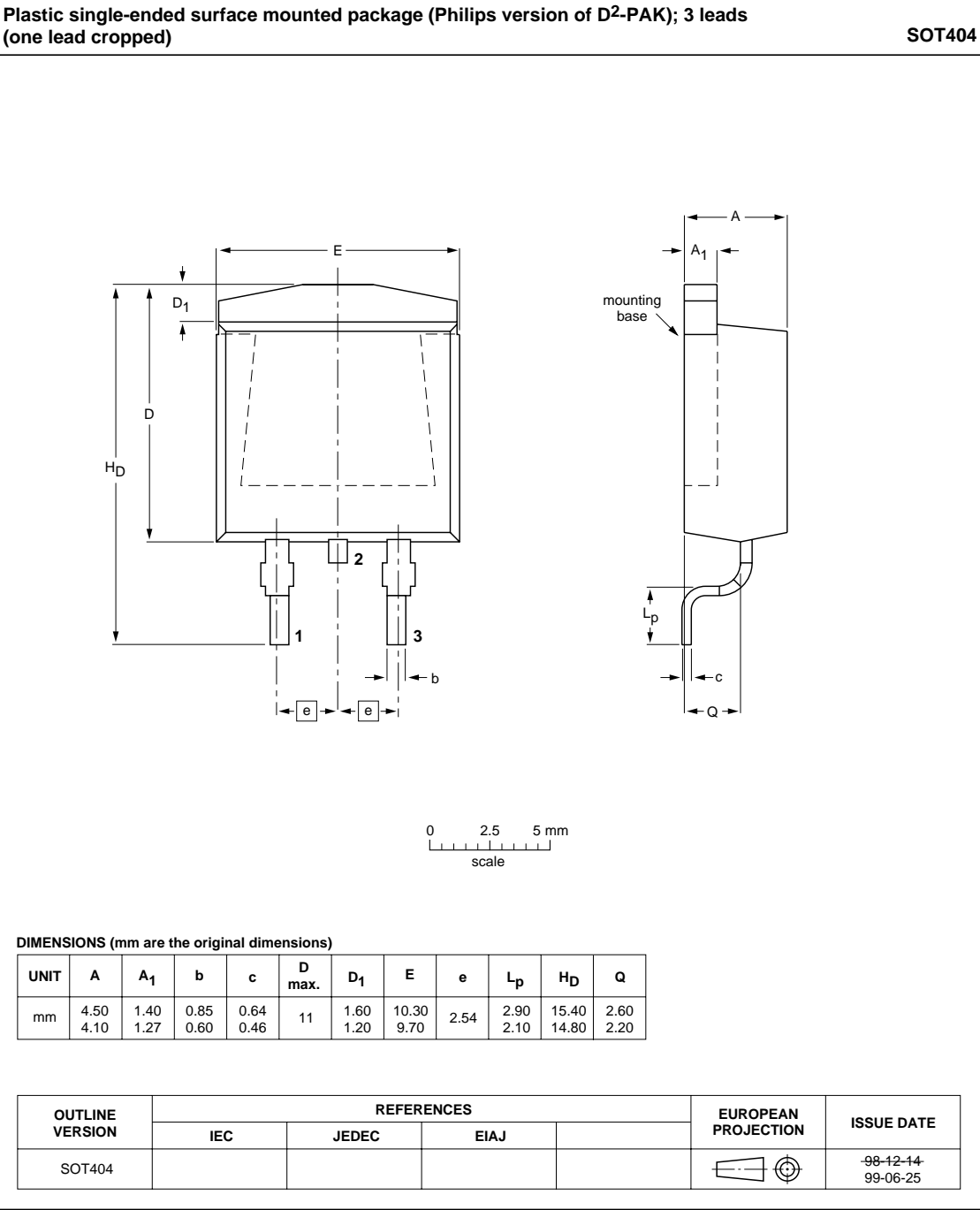


Fig.2. SOT404 surface mounting package¹, centre pin connected to mounting base.

¹ Epoxy meets UL94 V0 at 1/8". Net mass: 1.4 g
For soldering guidelines and SMD footprint design, please refer to Data Handbook SC18.

Logic level TOPFET SMD version of BUK119-50DL

BUK130-50DL

DEFINITIONS

DATA SHEET STATUS		
DATA SHEET STATUS ¹	PRODUCT STATUS ²	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A
Limiting values		
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.		
Application information		
Where application information is given, it is advisory and does not form part of the specification.		
© Philips Electronics N.V. 2001		
All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.		
The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.		

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

¹ Please consult the most recently issued datasheet before initiating or completing a design.

² The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.